

General Description

The Sanrise SRC60R082BT-GA is a high voltage power MOSFET, fabricated using advanced super junction technology. The resulting device has extremely low on resistance, low gate charge and fast switching time, making it especially suitable for applications which require superior power density and outstanding efficiency.

The SRC60R082BT-GA break down voltage is 600V and it has a high rugged avalanche characteristics.

The SRC60R082BT-GA is available in TO-247 package.

Features

- Ultra Low $R_{DS(ON)} = 82m\Omega @ V_{GS} = 10V$.
- Ultra Low Gate Charge, $Q_g = 110nC$ typ.
- Intrinsic Fast-Recovery Body Diode
- Fast switching capability
- Robust design with better EAS performance
- EMI Improved
- Qualified according to AEC Q101
- Green Product (RoHS compliant)

Application

- On-Board Charger
- DC/DC Converter
- Auxiliary Inverter

Symbol

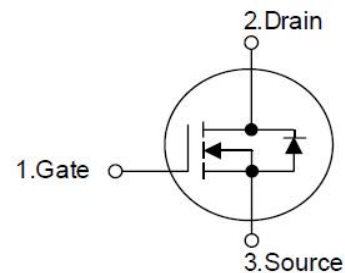


Figure 1 Symbol of SRC60R082BT-GA

Package Type

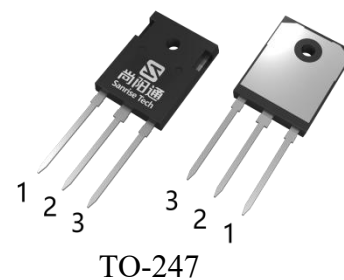
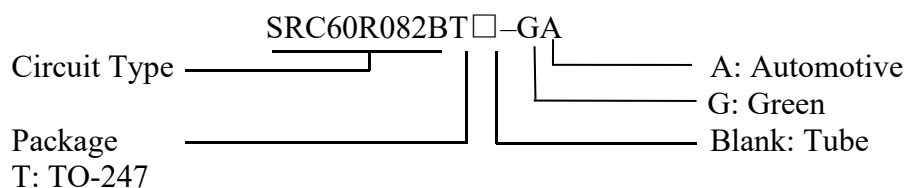


Figure 2 Package Type of SRC60R082BT-GA

Ordering Information



Package	Part Number	Marking ID	Packing Type
TO-247	SRC60R082BT-GA	SRC60R082BTGA	Tube

Absolute Maximum Ratings^{Note 1}

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	600	V
Gate-Source Voltage (static)		V_{GSS}	±20	V
Gate-Source Voltage (dynamic), AC($f > 1\text{Hz}$)		V_{GSS}	±30	V
Power Dissipation($T_C=25^\circ\text{C}, \text{TO-247}$)		P_{tot}	357	W
Continuous Drain Current	$T_C=25^\circ\text{C}$	I_D	45	A
	$T_C=100^\circ\text{C}$		28	
	$T_C=125^\circ\text{C}$		20.3	
Pulsed Drain Current (Note 2)		I_{DM}	135	A
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	125	mJ
Avalanche Energy, Single Pulse (Note 3)		E_{AS}	1280	mJ
Avalanche Energy, Repetitive (Note 2)		E_{AR}	0.6	mJ
Avalanche Current, Repetitive (Note 2)		I_{AR}	5.0	A
Continuous Diode Forward Current		I_S	45	A
Diode Pulse Current		$I_{S,PULSE}$	135	A
MOSFET dv/dt Ruggedness, $V_{DS} \leq 480\text{V}$		dv/dt	80	V/ns
Reverse Diode dv/dt, $V_{DS} \leq 480\text{V}, I_{SD} \leq I_D$		dv/dt	50	V/ns
Operating Junction Temperature		T_J	150	°C
Storage Temperature		T_{STG}	-55 to 150	°C
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	°C

Note:

- Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
- Repetitive Rating: Pulse width limited by maximum junction temperature
- $I_{AS} = 5\text{A}$, $V_{DD} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. Finish goods test condition.
- $I_{AS} = 16\text{A}$, $V_{DD} = 60\text{V}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$. Typical Eas.

Thermal characteristics

Parameter		Symbol	Min	Typ	Max	Unit
Thermal resistance, Junction-to-Case	TO-247	R_{thJC}			0.35	°C /W
Thermal resistance, Junction-to-Ambient	TO-247	R_{thJA}			58	°C /W

Electrical Characteristics
 $T_J = 25^{\circ}\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	600			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=600V, V_{GS}=0V$			10	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=20V, V_{DS}=0V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=-20V, V_{DS}=0V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=1.0mA$	3.0	4.0	5.0	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=24A$		60	82	mΩ
Gate Resistance	R_G	f=1MHz, Open Drain		1.0		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=25V, V_{GS}=0V, f=1MHz$		4.3		nF
Output Capacitance	C_{OSS}			2.0		nF
Reverse Transfer Capacitance	C_{RSS}			50		pF
Effective output capacitance, energy related ^{NOTE5}	$C_{O(er)}$	$V_{GS}=0V, V_{DS}=0\dots 480V$		94		pF
Effective output capacitance, time related ^{NOTE6}	$C_{O(tr)}$			550		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=400V, I_D=24A, R_G=3\Omega, V_{GS}=10V$		40		ns
Rise Time	t_r			18		
Turn-off Delay Time	$t_{d(off)}$			108		
Fall Time	t_f			8.0		
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DD}=480V, I_D=24A, V_{GS}=0 \text{ to } 10V$		28.1		nC
Gate to Drain Charge	Q_{gd}			56.0		
Gate Charge Total	Q_g			110		
Gate Plateau Voltage	$V_{plateau}$			6.5		V
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=24A$		0.9	1.1	V
Reverse Recovery Time	t_{rr}	$V_R=400V, I_F=24A, dI_F/dt=100A/\mu s$		141		ns
Reverse Recovery Charge	Q_{rr}			0.83		μC
Peak Reverse Recovery Current	I_{rrm}			11.8		A

Note:

 5. $C_{O(er)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 480V

 6. $C_{O(tr)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 480 V



Shenzhen Sanrise Technology Co., LTD

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